

Product / Process Change Notice

PCN No.: Q000-PCN-PA202005-03

Date: 2020-05-18

Change Title: To change the IC top marking company logo from Winbond to Nuvoton.

Change Classification: ☐ Major ☒ Minor

Change item: ☐ Design ☐ Raw Material ☐ Wafer FAB ☐ Package Assembly ☐ Testing ☒ Others: logo change.

Affected Product(s) :

All the package products with Winbond logo will be affected and the affected package type lists please refer to the Table I for more information.

Description of Change(s) :

To align with the company logo change, Nuvoton logo plans to implement and shows on IC package top marking to recognize the change. As to the difference, please refer to the Fig. 1 for more details.

Reason for Change(s) :

Due to the establishment of Nuvoton, the logo on package top marking will be introduced with new CIS (Corporate Identity System).

Impact of Change(s) : (positive & negative)

Form: Please refer to the Fig. 1 for comparison

Fit: No concern

Function: No concern

Reliability: No concern

Qualification Plan/ Results :

No product quality qualification is required and the changes made only to the appearance of package.

Implementation Plan :

The Nuvoton company logo marking goods will be started to ship to customer from June 28, 2020. As to the old Winbond logo marking goods, they will be kept on shipping until the inventory has been depleted. If the customer has any question, please contact the local sales for more information.

☐ Date Code: _____ onward ☐ Lot No.: _____ onward ☐ Implemented date: Jun 28, 2020

Originator:	H.Y. Lai / Q100	Approval:(QRA Director)	C.H. Shen/ Q000
Contact for Questions & Concerns	Name: <u>HYLai</u> TEL: <u>886-3-5770066</u> (ext. <u>31226</u>) FAX: <u>886-3-5792673</u> . Address: <u>No.4, Creation Rd. III Science-Based Industrial Park Hsinchu, Taiwan, R.O.C.,</u> E-mail: <u>hylai0@nuvoton.com.</u>		

Customer Comments:

Note: Please sign this notice, and return to Nuvoton contact within **10** days. If no response is received within **10** days, this Change Request will be assumed to meet your approval.

☐ Approval	☐ Disapproval	☐ Conditional Approval: _____.
Date: _____	Dept. name: _____	Person in charge: _____.

Follow-up and Tracing:

A. copies to

FAB : ☐ Integration _____ ☐ _____ ☐ _____ ☐ _____.

Test / Product: ☐ _____ ☐ _____ ☐ _____ ☐ _____.

Design/ Marketing: ☐ _____ ☐ _____ ☐ _____ ☐ _____.

Production control/ Others: ☐ _____ ☐ _____ ☐ _____ ☐ _____.

B. Changes:

1. Document / Test program:

Document No/ test program	Document name/ test program name	version		responsibor	Completed date	Remark
		before	after			
NA	NA	NA	NA	NA	NA	NA

Verified by: _____.

Table I: Affected part lists

Part No	Part No	Part No
W83527HG	W83627EHG	W83795ADG
W83601G	W83627HG-AW	W83795G
W83627DHG	W83627UHG	W83977AG-A
W83627DHG-P	W83782G	W83977EG-AW
W83627DHG-PT	W83793G	W83L603G

	Original Logo Mark	Nuvoton Logo Mark
Type A (SOP)	 A photograph of a Winbond SOP package. The top surface is marked with the Winbond logo, the part number W123456789AB, and the date code 710SA123456789AB2SB.	 A photograph of a Nuvoton SOP package. The top surface is marked with the Nuvoton logo, the part number W123456789AB, and the date code 710SA123456789AB2SB.
Type B (LQFP, SSOP, TSSOP, QFP)	 A photograph of a Winbond LQFP package. The top surface is marked with the Winbond logo, the part number W123456789AB, the date code 123456789AB2, and the date code 710SASB.	 A photograph of a Nuvoton LQFP package. The top surface is marked with the Nuvoton logo, the part number W123456789AB, the date code 123456789AB2, and the date code 710SASB.

Fig. 1 The logo change from Winbond to Nuvoton is shown on IC top mark.